



# 100% Material Declaration Data Sheet BGG560

PK217 (v1.0) February 20, 2007

Material Declaration Data Sheet

**Average Weight: 10.243 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.2814</b>	<b>2.75%</b>
	Silicon	7440-21-3	100.00		0.2814	
<b>Die Attach Material</b>					<b>0.0227</b>	<b>0.22%</b>
	Resin	Trade Secret	25.00		0.005675	
	Silver	7440-22-4	75.00		0.017025	
<b>Mold Compound</b>					<b>0.5334</b>	<b>5.21%</b>
	Resin	Trade Secret	26.00		0.138684	
	Silica	60676-86-0	74.00	Filler	0.394716	
<b>Dam</b>					<b>0.0138</b>	<b>0.13%</b>
	Resin	Trade Secret	28.00		0.003864	
	Silica	60676-86-0	72.00	Filler	0.009936	
<b>Laminate</b>					<b>0.8314</b>	<b>8.12%</b>
	BT (core)	Trade Secret			0.509	
	Solder Mask (EP)	Trade Secret			0.180	
	Copper	7440-50-8		Metal Layer	0.129	
	Nickel	7440-02-0		Metal Layer	0.010	
	Gold	7440-57-5		Metal Layer	0.003	
<b>Heat Spreader</b>					<b>7.2427</b>	<b>70.71%</b>
	Copper	7440-50-8	97.50		7.062	
	Iron	7439-89-6	2.35		0.170	
	Phosphorus	7723-14-0	0.03		0.002	
	Zinc	7440-66-6	0.12		0.009	
<b>Heat Spreader Adhesive</b>					<b>0.329</b>	<b>3.21%</b>
	Nickel	7440-02-0	100.00		0.0329	
<b>Gold Wire</b>					<b>0.0236</b>	<b>0.23%</b>
	Gold	74410-57-5	100.00		0.0236	
<b>Solder Balls</b>					<b>0.9648</b>	<b>9.42%</b>
	Tin	7440-31-5	95.50		0.921	
	Silver	7440-22-4	4.0		0.039	
	Copper	7440-50-8	0.5		0.005	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
2/20/07	1.0	Initial release.